

## Designing with Excelon™ LP SPI F-RAM™ Low-Power Modes

Author: Shivendra Singh

Associated Part Family: CY15x102Qx, CY15x104Qx, CY15x108Qx

AN225301 provides an overview of the three low-power modes of Cypress Excelon™ Low-Power SPI F-RAMs and their use case with examples showing advantages and disadvantages to help when selecting the appropriate low-power mode for power-efficient, battery-operated system designs.

### 1 Introduction

The Excelon LP SPI F-RAMs offer three low-power modes which include standby ( $I_{SB}$ ), deep-power-down ( $I_{DPD}$ ), and hibernate ( $I_{HIB}$ ). Any of these three low power modes can be effectively applied in system designs to optimize the system power consumption while the system is either in power saving mode or shutdown, thus can help enhancing the system battery life.

Standby mode is the default low-power mode for the SPI F-RAM when its chip-select ( $\overline{CS}$ ) pin is de-asserted to a logic HIGH to terminate an ongoing device operation. If the device is in standby mode,  $\overline{CS}$  transition from HIGH to LOW exits the standby mode and the device is immediately available for access. The deep-power-down or hibernate mode entry is command (opcode) based; therefore, the SPI F-RAM enters either deep-power-down or hibernate mode only after specific command is issued, followed by  $\overline{CS}$  transitioning to HIGH.

The deep-power-down or hibernate mode exits when  $\overline{CS}$  is de-asserted to logic LOW, like when exiting the standby mode. However, exiting from deep-power-down or hibernate mode is not immediate and exit delay is associated with an internal wake up cycle time. This means that even though the deep-power-down and hibernate modes draw lower currents than standby mode, they may not necessarily offer the lowest total energy consumption always because of the overheads associated with the low-power mode entry and exit timings.

This application note guides you through the details of Excelon LP SPI F-RAM low-power modes, analyzes various use cases, and highlights associated overheads with each low-power mode based upon the system duty cycle to access the SPI F-RAM. Selecting an effective low-power mode of operation of the SPI F-RAM can help reduce the total system power in power-sensitive, battery-operated systems.

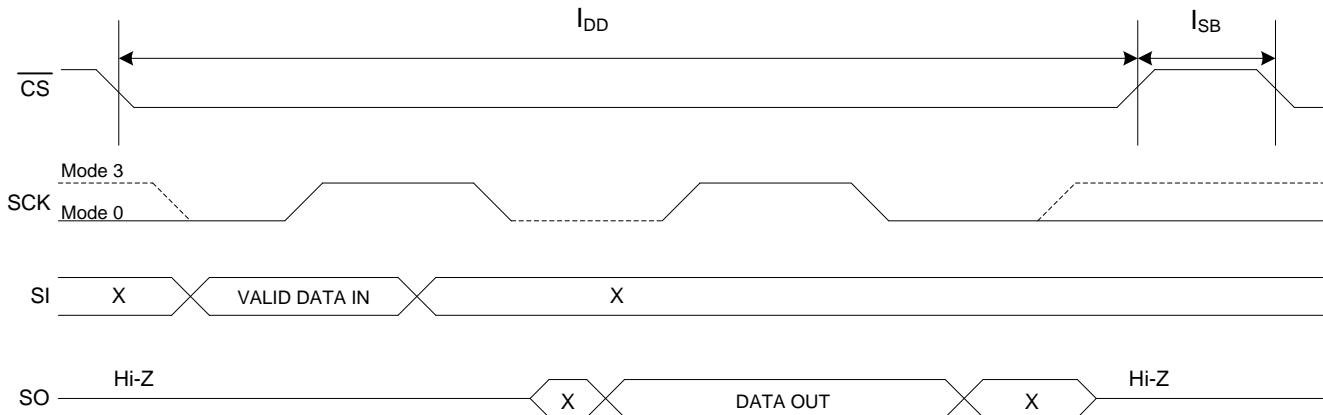
### 2 Low-Power Modes in Excelon LP F-RAMs

This section describes in detail the three low-power modes supported by Excelon LP SPI F-RAM.

#### 2.1 Standby Mode

Standby mode is the default power saving mode when any normal memory operation is inhibited. Standby mode is enabled by de-asserting the Chip Select pin ( $\overline{CS}$ ) to a logic HIGH. [Figure 1](#) highlights instances when the SPI F-RAM enters and exits the standby mode.

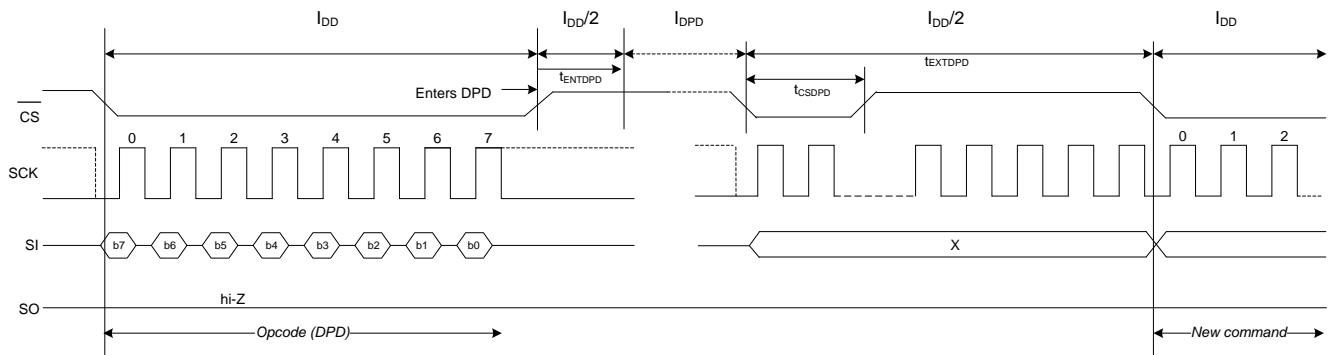
Figure 1. Excelon LP SPI F-RAM Standby Mode



## 2.2 Deep-Power-Down (DPD) Mode

Deep-power-down mode is a lower power mode than the standby mode. The SPI F-RAM device enters deep-power-down mode with the Deep Power Down Enable opcode (DPD). Once the device receives the DPD opcode followed by  $\overline{CS}$  de-asserted to a logic HIGH, the device current drops to deep-power-down mode current ( $I_{DPD}$ ) after  $t_{ENTDPD}$  time. The device wakes up from deep-power-down mode only after a logic LOW pulse of width  $t_{CSDPD}$  (max) is applied on the  $\overline{CS}$  pin. It takes  $t_{EXTDPD}$  (max) time to wake up from deep-power-down mode. Table 1 and Table 2 show Excelon LP SPI F-RAM deep-power-down mode enter and exit timings. Figure 2 highlights instances when the SPI F-RAM enters and exits deep-power-down mode.

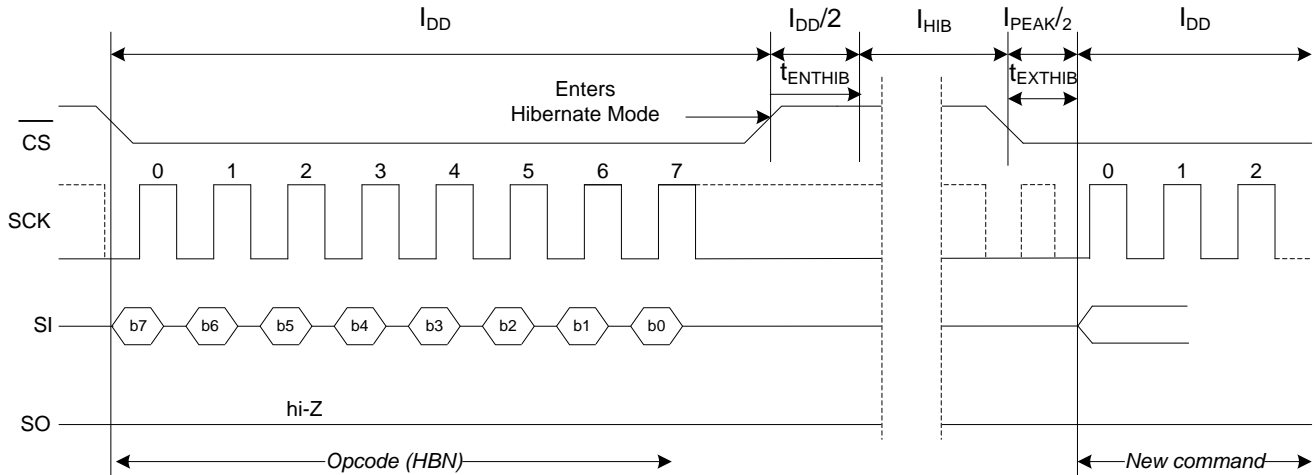
Figure 2. Excelon LP SPI F-RAM Deep-Power-Down (DPD) Mode



## 2.3 Hibernate Mode

Hibernate mode is the lowest power mode in Excelon LP SPI F-RAMs. The SPI F-RAM device enters hibernate mode with the Hibernate Enable opcode (HBN). Once the device receives the HBN command followed by  $\overline{CS}$  transitioning to a logic HIGH, the device current drops to hibernate mode current ( $I_{HIB}$ ) after the  $t_{ENTHIB}$  time. The device wakes up from hibernate mode only after the  $\overline{CS}$  pin is asserted to a logic LOW. It takes the  $t_{EXTHIB}$  (max) time to wake up from hibernate mode. Table 1 and Table 2 show Excelon LP SPI F-RAM hibernate mode enter and exit timings. Figure 3 highlights instances when the SPI F-RAM enters and exits hibernate mode.

Figure 3. Excelon LP SPI F-RAM Hibernate Mode



### 3 Use Case Analysis

Figure 1 to Figure 3 illustrate different power modes of SPI F-RAMs and highlight specific current consumed in each power mode. This section analyzes three different use cases based upon system duty cycle to understand total current consumption (active + low-power mode). A point to note is that the energy calculations provided in this section include energy consumption for the SPI F-RAM device alone; to get the combined system-level power, you should include the host controller and other associated circuits also.

Table 2 lists the entry and exit timings for various low-power modes as well as the associated currents which are the basis for energy calculations under various use-case scenarios. The data provided in Table 2 has considered the specifications of the SPI F-RAM with inrush current control (CY15B104QI) which are primarily designed for battery powered applications. However, the energy calculation method used in this application note will also apply as is for SPI F-RAM devices with non-inrush current control.

Table 1. Low-Power Mode Enter/Exit Timings

Low-Power Modes	Enter Time	Exit Time
Standby mode	Immediate	Immediate
Deep-power-down mode	$\leq t_{ENTDPD}$	$\leq t_{EXTDPD}$
Hibernate mode	$\leq t_{ENTHIB}$	$\leq t_{EXTHIB}$

Table 2. Low-Power Mode Specifications for Energy Calculation

SPI F-RAM Specification (CY15B104QI)	Value	Unit
$V_{DD}$	3.0	V
$V_{DD}$ supply current - $I_{DD}$ @ 3 MHz	500	$\mu A$
Inrush current ( $I_{PEAK}$ )	1600	$\mu A$
Average current during wakeup from hibernate ( $I_{PEAK}/2$ )	800	$\mu A$
Average current during wakeup from deep-power-down ( $I_{DD}/2$ )	250	$\mu A$
$V_{DD}$ Standby current ( $I_{SB}$ )	2.6	$\mu A$
Deep-power-down-current ( $I_{DPD}$ )	0.8	$\mu A$

SPI F-RAM Specification (CY15B104QI)	Value	Unit
Hibernate mode current ( $I_{HBN}$ )	0.1	$\mu\text{A}$
Time to enter deep-power-down ( $t_{ENTDPD}$ )	3	$\mu\text{s}$
Time to enter hibernate ( $t_{ENTHIBN}$ )	3	$\mu\text{s}$
Time to exit deep-power-down ( $t_{EXTDPD}$ )	150	$\mu\text{s}$
Time to exit hibernate ( $t_{EXTHBN}$ )	5000	$\mu\text{s}$

### 3.1 Energy Calculation Equation

$E = V * I * T$ , where:

E = Energy in  $\mu\text{J}$ ;

V = Supply voltage  $V_{DD}$  in volt;

I = Current in mA;

T = Time in millisecond;

Active mode energy =  $V_{DD} * \text{Active mode Current} * \text{Time in active mode}$

$$= V_{DD} * I_{DD} * \text{Time in active mode}$$

Standby mode energy =  $V_{DD} * \text{Standby mode Current} * \text{Time in standby mode}$

$$= V_{DD} * I_{SB} * \text{Time in standby mode}$$

Deep-power-down mode energy = Energy to enter deep-power-down + Energy while in deep-power-down + Energy to exit deep-power-down

$$= V_{DD} * I_{DD} / 2 * t_{ENTDPD} + V_{DD} * I_{DPD} * \text{Time in deep-power-down} + V_{DD} * I_{DD} / 2 * t_{EXTDPD}$$

Hibernate mode energy = Energy to enter hibernate + Energy while in hibernate + Energy to exit hibernate

$$= V_{DD} * I_{DD} / 2 * t_{ENTHIB} + V_{DD} * I_{HBN} * \text{Time in hibernate} + V_{DD} * I_{DD} / 2 * t_{EXTHIB}$$

### 3.2 Use Case 1: Sampling Interval Every 10 milliseconds

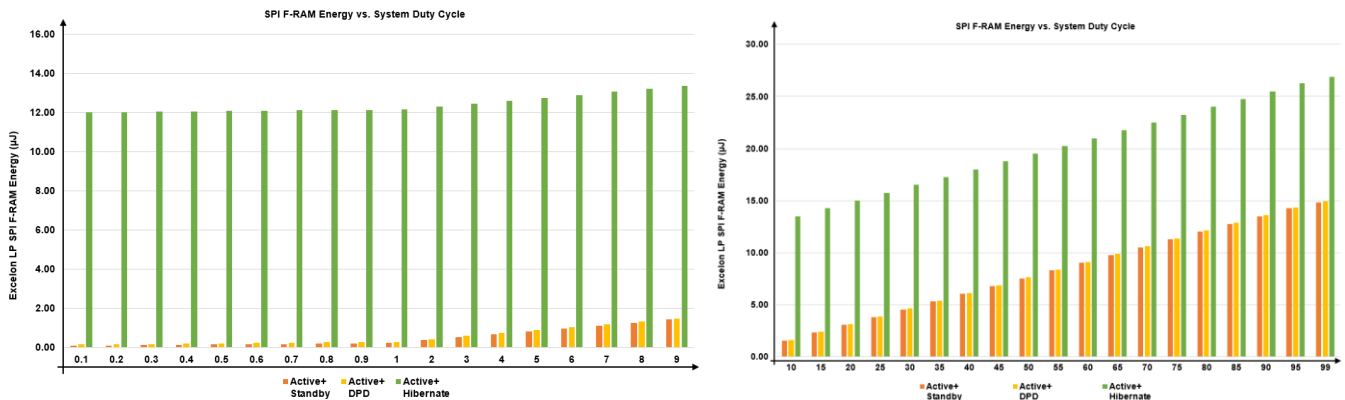
This use case analysis considers a sampling interval where the system wakes up every 10 milliseconds, enters active mode, stays in active mode for a percentage of the sampling interval and the remaining time is in standby, deep-power-down or hibernate mode, and compares the total energy consumed (active + low-power) across all three low-power modes for varying duty cycles.

Table 3. Use Case 1: Energy Calculations in Different Low-Power Modes

System duty cycle	SPI F-RAM different operating mode timings (ms)				SPI F-RAM Active + low power mode energy (E = V*I*T) - μJ		
	System Active (%)	When In Active Mode	When In Stdby Mode	When In DPD Mode	When In Hibernate Mode	Active+ Standby	Active+ DPD
0.1	0.01	9.99	9.837	4.987	0.09	0.15	12.02
0.2	0.02	9.98	9.827	4.977	0.11	0.17	12.04
0.3	0.03	9.97	9.817	4.967	0.12	0.18	12.05
0.4	0.04	9.96	9.807	4.957	0.14	0.20	12.07
0.5	0.05	9.95	9.797	4.947	0.15	0.21	12.08
0.6	0.06	9.94	9.787	4.937	0.17	0.23	12.10
0.7	0.07	9.93	9.777	4.927	0.18	0.24	12.11
0.8	0.08	9.92	9.767	4.917	0.20	0.26	12.13
0.9	0.09	9.91	9.757	4.907	0.21	0.27	12.14
1	0.1	9.9	9.747	4.897	0.23	0.29	12.16
2	0.2	9.8	9.647	4.797	0.38	0.44	12.31
3	0.3	9.7	9.547	4.697	0.53	0.59	12.46
4	0.4	9.6	9.447	4.597	0.67	0.74	12.61
5	0.5	9.5	9.347	4.497	0.82	0.89	12.76
6	0.6	9.4	9.247	4.397	0.97	1.04	12.91
7	0.7	9.3	9.147	4.297	1.12	1.19	13.06
8	0.8	9.2	9.047	4.197	1.27	1.34	13.21
9	0.9	9.1	8.947	4.097	1.42	1.49	13.36
10	1	9	8.847	3.997	1.57	1.64	13.51
15	1.5	8.5	8.347	3.497	2.32	2.38	14.26
20	2	8	7.847	2.997	3.06	3.13	15.01
25	2.5	7.5	7.347	2.497	3.81	3.88	15.76
30	3	7	6.847	1.997	4.55	4.63	16.51
35	3.5	6.5	6.347	1.497	5.30	5.38	17.26
40	4	6	5.847	0.997	6.05	6.13	18.01
45	4.5	5.5	5.347	0.497	6.79	6.88	18.76
50	5	5	4.847	0	7.54	7.63	19.51
55	5.5	4.5	4.347	0	8.29	8.38	20.26
60	6	4	3.847	0	9.03	9.12	21.01
65	6.5	3.5	3.347	0	9.78	9.87	21.76
70	7	3	2.847	0	10.52	10.62	22.51
75	7.5	2.5	2.347	0	11.27	11.37	23.26
80	8	2	1.847	0	12.02	12.12	24.01
85	8.5	1.5	1.347	0	12.76	12.87	24.76
90	9	1	0.847	0	13.51	13.62	25.51
95	9.5	0.5	0.347	0	14.25	14.37	26.26
99	9.9	0.1	0	0	14.85	14.96	26.86

**Note:** The highlighted 0 millisecond for both deep-power-down and hibernate modes indicates that the SPI F-RAM device doesn't have sufficient time to stay in respective low-power mode for those specific duty cycles.

Figure 4. Use Case 1: Energy Calculations in Different Low-Power Modes



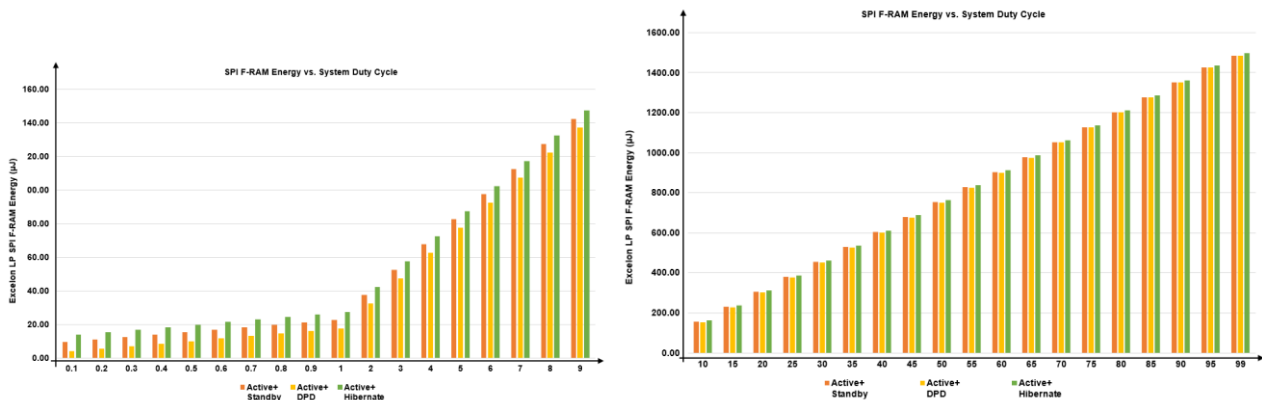
### 3.3 Use Case 2: Sampling Interval Every Second

This use case analysis considers a sampling interval where the system wakes up every second, enters active mode, stays in active mode for a percentage of the sampling interval and the remaining time is in standby, deep-power-down, or hibernate mode, and compares the total energy consumed (active + low-power) across all three low-power modes for varying duty cycles.

Table 4. Use Case 2: Energy Calculations in Different Low-Power Modes

System duty cycle	SPI F-RAM different operating mode timings (ms)				SPI F-RAM Active + low power mode energy (E = V*I*T) - μJ		
System Active (%)	When In Active Mode	When In Stdby Mode	When In DPD Mode	When In Hibernate Mode	Active+ Standby	Active+ DPD	Active+ Hibernate
0.1	1	999	998.847	993.997	9.29	4.01	13.81
0.2	2	998	997.847	992.997	10.78	5.51	15.31
0.3	3	997	996.847	991.997	12.28	7.01	16.80
0.4	4	996	995.847	990.997	13.77	8.50	18.30
0.5	5	995	994.847	989.997	15.26	10.00	19.80
0.6	6	994	993.847	988.997	16.75	11.50	21.30
0.7	7	993	992.847	987.997	18.25	13.00	22.80
0.8	8	992	991.847	986.997	19.74	14.50	24.30
0.9	9	991	990.847	985.997	21.23	15.99	25.80
1	10	990	989.847	984.997	22.72	17.49	27.30
2	20	980	979.847	974.997	37.64	32.47	42.30
3	30	970	969.847	964.997	52.57	47.44	57.30
4	40	960	959.847	954.997	67.49	62.42	72.29
5	50	950	949.847	944.997	82.41	77.39	87.29
6	60	940	939.847	934.997	97.33	92.37	102.29
7	70	930	929.847	924.997	112.25	107.35	117.28
8	80	920	919.847	914.997	127.18	122.32	132.28
9	90	910	909.847	904.997	142.10	137.30	147.28
System Active (%)	When In Active Mode	When In Stdby Mode	When In DPD Mode	When In Hibernate Mode	Active+ Standby	Active+ DPD	Active+ Hibernate
10	100	900	899.847	894.997	157.02	152.27	162.28
15	150	850	849.847	844.997	231.63	227.15	237.26
20	200	800	799.847	794.997	306.24	302.03	312.25
25	250	750	749.847	744.997	380.85	376.91	387.23
30	300	700	699.847	694.997	455.46	451.79	462.22
35	350	650	649.847	644.997	530.07	526.67	537.20
40	400	600	599.847	594.997	604.68	601.55	612.19
45	450	550	549.847	544.997	679.29	676.43	687.17
50	500	500	499.847	494.997	753.90	751.31	762.16
55	550	450	449.847	444.997	828.51	826.19	837.14
60	600	400	399.847	394.997	903.12	901.07	912.13
65	650	350	349.847	344.997	977.73	975.95	987.11
70	700	300	299.847	294.997	1052.34	1050.83	1062.10
75	750	250	249.847	244.997	1126.95	1125.71	1137.08
80	800	200	199.847	194.997	1201.56	1200.59	1212.07
85	850	150	149.847	144.997	1276.17	1275.47	1287.05
90	900	100	99.847	94.997	1350.78	1350.35	1362.04
95	950	50	49.847	44.997	1425.39	1425.23	1437.02
99	990	10	9.847	4.997	1485.08	1485.14	1497.01

Figure 5. Use Case 2: Energy Calculations in Different Low-Power Modes



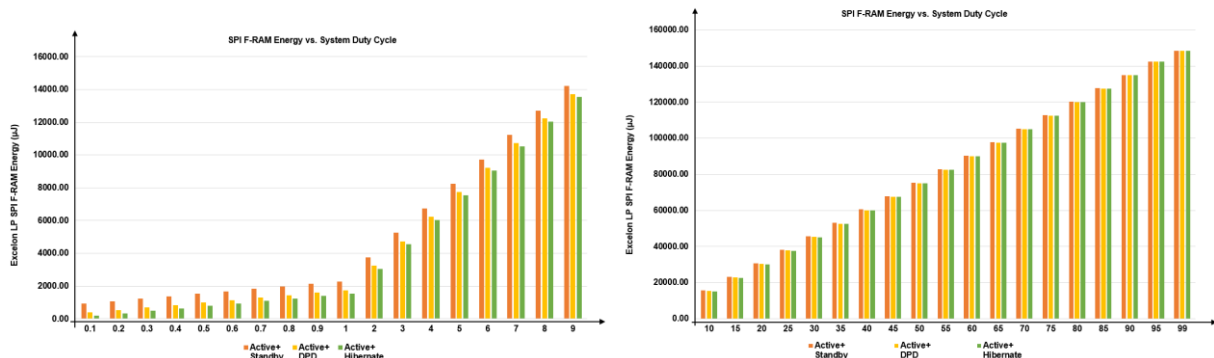
### 3.4 Use Case 3: Sampling Interval Every 100 Seconds

This use case analysis considers a sampling interval where the system wakes up every 100 seconds, enters active mode, stays in active mode for a percentage of the sampling interval and the remaining time is in standby, deep-power-down, or hibernate mode, and compares the total energy consumed (active + low-power) across all three low-power modes for varying duty cycles.

Table 5. Use Case 3: Energy Calculations in Different Low-Power Modes

System duty cycle	SPI F-RAM different operating mode timings (ms)				SPI F-RAM Active + low power mode energy (E = V*I*T) - μJ		
	When In Active Mode	When In Stdby Mode	When In DPD Mode	When In Hibernate Mode	Active+ Standby	Active+ DPD	Active+ Hibernate
0.1	100	99900	99899.847	99894.997	929.22	389.87	191.98
0.2	200	99800	99799.847	99794.997	1078.44	539.63	341.95
0.3	300	99700	99699.847	99694.997	1227.66	689.39	491.92
0.4	400	99600	99599.847	99594.997	1376.88	839.15	641.89
0.5	500	99500	99499.847	99494.997	1526.10	988.91	791.86
0.6	600	99400	99399.847	99394.997	1675.32	1138.67	941.83
0.7	700	99300	99299.847	99294.997	1824.54	1288.43	1091.80
0.8	800	99200	99199.847	99194.997	1973.76	1438.19	1241.77
0.9	900	99100	99099.847	99094.997	2122.98	1587.95	1391.74
1	1000	99000	98999.847	98994.997	2272.20	1737.71	1541.71
2	2000	98000	97999.847	97994.997	3764.40	3235.31	3041.41
3	3000	97000	96999.847	96994.997	5256.60	4732.91	4541.11
4	4000	96000	95999.847	95994.997	6748.80	6230.51	6040.81
5	5000	95000	94999.847	94994.997	8241.00	7728.11	7540.51
6	6000	94000	93999.847	93994.997	9733.20	9225.71	9040.21
7	7000	93000	92999.847	92994.997	11225.40	10723.31	10539.91
8	8000	92000	91999.847	91994.997	12717.60	12220.91	12039.61
9	9000	91000	90999.847	90994.997	14209.80	13718.51	13539.31
10	10000	90000	89999.847	89994.997	15702.00	15216.11	15039.01
15	15000	85000	84999.847	84994.997	23163.00	22704.11	22537.51
20	20000	80000	79999.847	79994.997	30624.00	30192.11	30036.01
25	25000	75000	74999.847	74994.997	38085.00	37680.11	37534.51
30	30000	70000	69999.847	69994.997	45546.00	45168.11	45033.01
35	35000	65000	64999.847	64994.997	53007.00	52656.11	52531.51
40	40000	60000	59999.847	59994.997	60468.00	60144.11	60030.01
45	45000	55000	54999.847	54994.997	67929.00	67632.11	67528.51
50	50000	50000	49999.847	49994.997	75390.00	75120.11	75027.01
55	55000	45000	44999.847	44994.997	82851.00	82608.11	82525.51
60	60000	40000	39999.847	39994.997	90312.00	90096.11	90024.01
65	65000	35000	34999.847	34994.997	97773.00	97584.11	97522.51
70	70000	30000	29999.847	29994.997	105234.00	105072.11	105021.01
75	75000	25000	24999.847	24994.997	112695.00	112560.11	112519.51
80	80000	20000	19999.847	19994.997	120156.00	120048.11	120018.01
85	85000	15000	14999.847	14994.997	127617.00	127536.11	127516.51
90	90000	10000	9999.847	9994.997	135078.00	135024.11	135015.01
95	95000	5000	4999.847	4994.997	142539.00	142512.11	142513.51
99	99000	1000	999.847	994.997	148507.80	148502.51	148512.31

Figure 6. Use Case 3: Energy Calculations in Different Low-Power Modes



### 3.5 Use Case Analysis Summary

The three low-power mode analyses show that SPI F-RAM energy efficiency primarily varies with SPI F-RAM active to low-power mode transition frequency (or sampling interval) and the duty cycle (percentage of the time SPI F-RAM goes into active mode for every sampling interval). Table 6 summarizes all the three use cases and recommended SPI F-RAM low-power mode for each use case. Point to note here is that the recommendations are purely based on power efficiency. Other system requirements should override these recommendations whenever necessary.

Table 6. SPI F-RAM Low-Power Mode Use Case Analysis Summary

Sampling Interval (Ts)	Duty Cycle	Standby	Deep-power-down	Hibernate	Comment
Ts < 25 ms	<10%	✓			
	>10%	✓	✓		Deep-power-down takes $t_{EXTDPD}$ time to wake.
25 ms ≤ Ts < 10,000 ms	<10%		✓		
	>10%	✓	✓	✓	Deep-power-down and hibernate take $t_{EXTDPD}$ and $t_{EXTHBN}$ time to wake.
Ts ≥ 10,000 ms	<10%			✓	
	>10%	✓	✓	✓	Deep-power-down and hibernate take $t_{EXTDPD}$ and $t_{EXTHBN}$ time to wake.

**Use case 1** – Table 3 and energy comparison graphs in Figure 4 show that when the system is accessing SPI F-RAM frequently (i.e., every 25 milliseconds or even faster), keeping the SPI F-RAM in standby mode is more energy efficient than the other two low-power modes. Using hibernate mode should be avoided in this use case. In addition, unlike deep-power-down and hibernate mode, there is no wakeup time penalty when using standby mode.

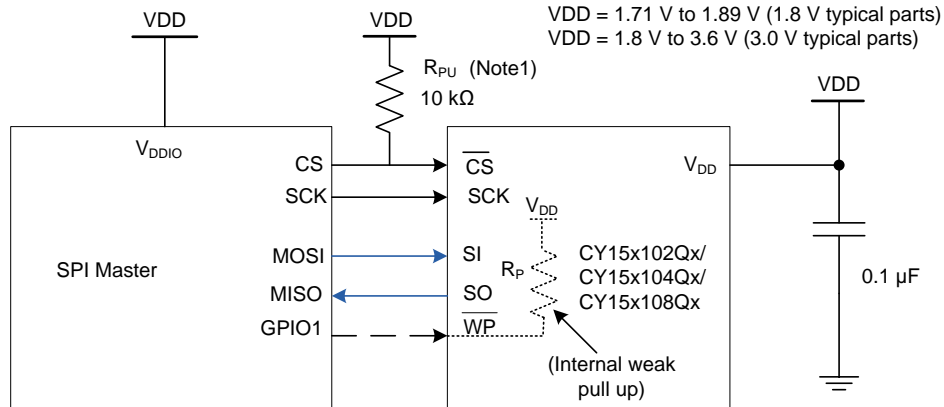
**Use case 2** – Table 4 and energy comparison graphs in Figure 5 show that when the system is accessing SPI F-RAM less frequently than in Use Case 1 (i.e., every 10 seconds or faster down to 25 milliseconds), keeping the SPI F-RAM in deep-power-down mode is more energy efficient than the other two low-power modes. However, exiting deep-power-down mode takes  $t_{EXTDPD}$  time before the device is ready for access, which needs to be considered in the system design.

**Use case 3** – Table 5 and energy comparison graphs in Figure 6 show that when when the system is accessing SPI F-RAM at a slow interval (i.e., every 10 seconds or slower), putting the SPI F-RAM in hibernate mode is more energy efficient than the other two low-power modes. However, exiting hibernate mode takes  $t_{EXTHBN}$  time before device is ready for access, which needs to be considered in the system design.

## 4 Other Considerations for Low-Power Mode Current Consumption

This section summarizes other system considerations that can influence the low-power measurements in Excelon LP SPI F-RAMs. Figure 7 shows an example of SPI F-RAM interface with a SPI host controller.

Figure 7. System Interface with SPI F-RAM



The signal and device nomenclature used in Figure 7 is as follows:

*MOSI*: Master-Out-Slave-In; *MISO*: Master-In-Slave-Out

**CY15x102Qx/CY15x104Qx/CY15x108Qx** – Excelon LP SPI F-RAMs including Inrush current controlled parts.

CY15V102Qx /CY15V104Qx/ CY15V108Qx – 1.8 V typical  $V_{DD}$  parts

CY15B102Qx /CY15B104Qx/ CY15B108Qx – 3.3 V typical  $V_{DD}$  parts

Data lines (Input, Output)      —————

Control line ( $\overline{CS}$  and SCK)     

(Optional connections)      - - - - -

System conditions that can influence the SPI F-RAM current measurements are described below:

1. Operating voltage ( $V_{DD}$ ) is outside datasheet limits.
2. Input voltage not swinging to appropriate logic levels of SPI F-RAM.
3. The  $\overline{WP}$  input pin provides an on-chip internal weak pull-up ( $R_P$ ) to  $V_{DD}$ , as shown in Figure 7. Therefore, if this pin is biased to a logic HIGH, the input voltage level must at  $V_{DD}$  to avoid any current leakage through  $R_P$ . If the  $\overline{WP}$  is not controlled, it is recommended to leave the pin to floating or short to  $V_{DD}$ .

## Document History

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Document Number: 002-25301

Revision	ECN	Orig. of Change	Submission Date	Description of Change
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Cypress Semiconductor  
198 Champion Court  
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